

CONSTRUCTION OF ELECTRONIC PARTS

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Abstract of JP 60049638 (A)

PURPOSE: To attain rapidly positioning of an electronic parts by a method wherein spherical bumps are formed to the bonding terminals of an LSI, and pin holes are formed to a corresponding wiring substrate. CONSTITUTION: Recess shapes 15 are formed previously at the bonding positions of wiring terminals 13. To form the shapes thereof, after the terminals 13 are formed, an etching mask is covered thereon, and windows are opened in a pin hole type in the mask only at the parts corresponding to the bonding positions. Etching is performed, and semispherical recess parts 15 are formed only at the parts opened with the windows according to half etching. The bumps 12 of an LSI11 formed in a semispherical type are positioned to be bonded to the terminals 13 formed in such a way.

